



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Drill, C. et al.

Serial No. : 08/824,633

Group Art Unit : 3724

Filed : 03/27/97

Examiner : Rachuba, M.

For : A CUSTOMIZED POLISHING PAD FOR SELECTIVE PROCESS
PERFORMANCE DURING CHEMICAL MECHANICAL
POLISHING

AMENDMENT AND RESPONSE

Assistant Commissioner for Patents & Trademarks
Washington, D.C. 20231

Sir:

In response to the Office Action mailed 03/08/01, please amend the
above-referenced Application as follows:

IN THE CLAIMS

✓
Please add the following new Claim:

Sub 21
-- 21. (New) A process specific polishing pad having a plurality of
regions configured to implement different polishing hardness on the surface of a
wafer, the process specific polishing pad comprising:

21
a polishing pad having an overlying layer, said overlying layer being
uniform and homogenous across a polishing surface of said overlying layer, said
polishing surface adapted to frictionally contact a wafer as said wafer is
polished in said wafer polishing machine; and

said polishing surface having a plurality of regions, each of said plurality
of regions configured to achieve a specific hardness effect by using a respective

20/June E
8/15/01
Hart
8/16/01
RECEIVED
AUG 14 2001
TC 3700 MAIL ROOM